

LTM4643 77LD LGA 15mm X 9mm X 1.82mm (TABLE OF MATERIAL DECLARATION)

This Package is RoHS compliant per EU RoHS Directive 2003/95/EC.

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+)
polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.1170	Bismaleimide/Triazine Resin/Filler Substances (Silica Crystalline)	105391-33-1 1156-51-0/9003-36-5/21645-51-2 *non-disclosure	0.03040	25.99
				Continuous Filament Fiber Glass	65997-17-3	0.02696	23.04
				Copper Metal	7440-50-8	0.04318	36.91
				Zinc	7440-66-6	0.00001	0.01
				Chromium(III) oxide	1308-38-9	0.00000	0.00
				Bisphenol A epoxyresin	25068-38-6	0.00001	0.01
				Epoxy Resin	*non-disclosure	0.00006	0.05
				Imidazole system curing reagent	*non-disclosure	0.00001	0.01
				Silica amorphous	7631-86-9	0.00008	0.07
				Acrylic Resin	*non-disclosure	0.00838	7.16
				Copper Compounds	147-14-8	0.00004	0.03
				Barium Compounds	7727-43-7	0.00439	3.76
				Talc;not containing fibers like asbestos	14807-96-6	0.00051	0.43
				Aromatic carbonyl compounds	non-disclosure	0.00048	0.41
				Cyanoguanidine	461-58-5	0.00001	0.01
				Amine compounds	*non-disclosure	0.00006	0.05
				Leveling agent and others	*non-disclosure	0.00019	0.16
				Nickel	7440-02-0	0.00196	1.67
				Phosphorus	7723-14-0	0.00015	0.13
				Gold	7440-57-5	0.00009	0.08
				Palladium	2023568	0.00003	0.02
				**Ecotoxic substances	7439-92-1	0.00000	0.00
2	Solder Paste	Alloy	0.0046	Tin (Sn)	7440-31-5	0.00437	95.00
				Antimony (Sb)	7440-36-0	0.00023	5.00
3	Components	Passive/Active	0.2354	Iron Powder (Fe)	7439-89-6	0.16761	71.19
				Copper (Cu)	7440-50-8	0.04804	20.40
				Nickel (Ni)	7440-02-0	0.00236	1.00
				Tin (Sn)	7440-31-5	0.00193	0.82
				Ceramic (Ba) Compounds	12047-27-7	0.01551	6.59
4	Active Ics	Silicon	0.0108	Silicon (Si)	7440-21-3	0.01084	100.00
5	Wire	Gold	0.0032	Gold (Au)	7440-57-5	0.00325	99.99
6	Encapsulation	Epoxy Resin	0.3325	Fused Silica	60676-86-0	0.25665	77.20
				Epoxy Resin	*non-disclosure	0.02959	8.90
				Phenol Resin	*non-disclosure	0.02959	8.90
				Crytalline Silica	14808-60-7	0.00997	3.00
				Carbon Black	1333-86-4	0.00166	0.50
				Metal Hydroxide	*non-disclosure	0.00499	1.50
Total Package Weight			0.7036				

Note: Composition derived from MSDS and material C of C from Vendors

Component Weight based on assembly of generic parts